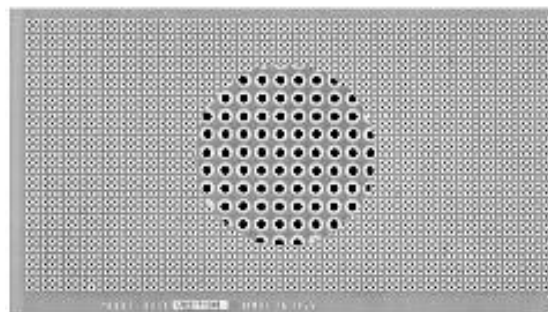


## 8010 4.0" x 13.0"

**Circuit Pattern:** Pad-Per-Hole  
**Contacts:** N/A  
**Width/Thick:** 12.86"/.062"  
**Height:** 4.00"  
**Contacts:** N/A  
**16-Pin DIP Capacity:** 124  
**Material:** FR4 Epoxy Glass  
**Wire-Wrap Terminals:** T44, T46, T49, T68,  
**Solder Terminals:** T42-1  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

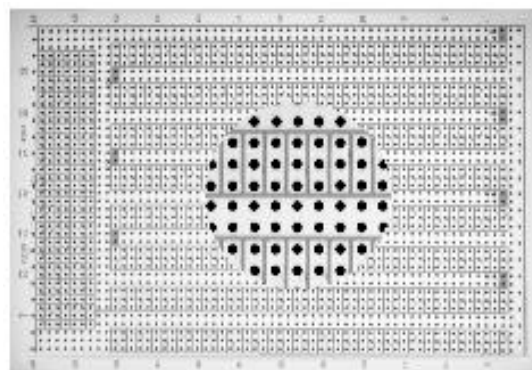
- Precision-Drilled, plated-thru holes
- 0.080" diameter, isolated solder pad around each hole
- Board size and surface area approximate Macintosh II specifications
- Unrestricted component placement



## 8001 4.50" x 6.5"

**Circuit Pattern:** 3-Hole Solder Pad  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 20  
**Material:** CEM-1  
**Solder Terminals:** T42-1, K24C, K31C  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

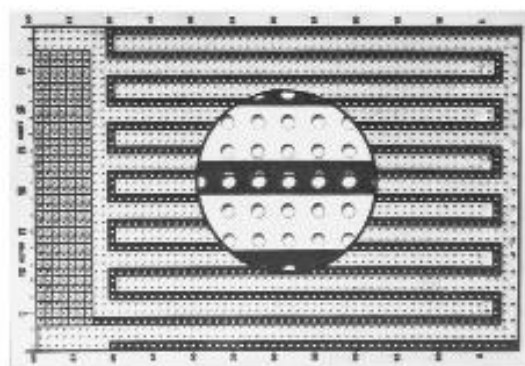
- Circuit pattern etched onto wiring side only
- Solder mount DIP sockets or IC devices with any lead spacing
- 3-hole solder pads (0.28" X 0.080") for interconnecting multiple component leads



## 8002 4.5" x 6.5"

**Circuit Pattern:** Interleaved Buses  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 36  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

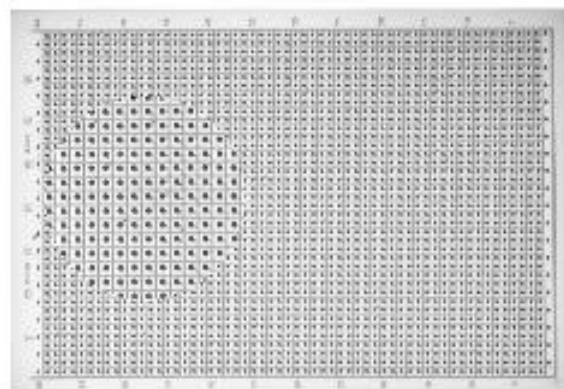
- Ideal for wire-wrap applications
- Power and ground buses etched onto wiring side only
- Bus surfaces solder coated for user convenience
- Mount components with 0.3", 0.6" and 0.9" lead spacing
- I/O area with solder pads for mounting connector

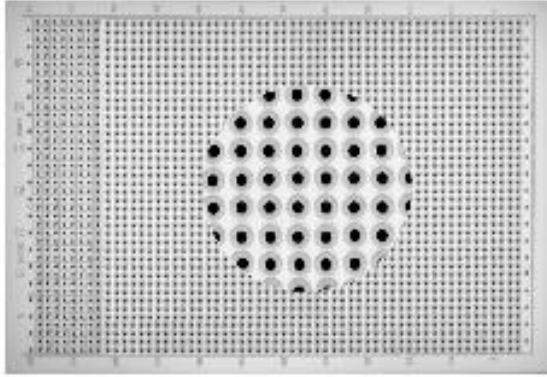


## 8003 4.5" x 6.5"

**Circuit Pattern:** Pad-Per-Hole  
**Contacts:** N/A  
**Width/Thick:** 6.50"/.062"  
**Height:** 4.50"  
**16-Pin DIP Capacity:** 60  
**Material:** CEM-1  
**Solder Terminals:** T42-1  
**Wire-Wrap Terminals:** T44, T46, T49, T68  
**Wire-Wrap Socket Pins:** R32  
**Hole Diameter:** .042"

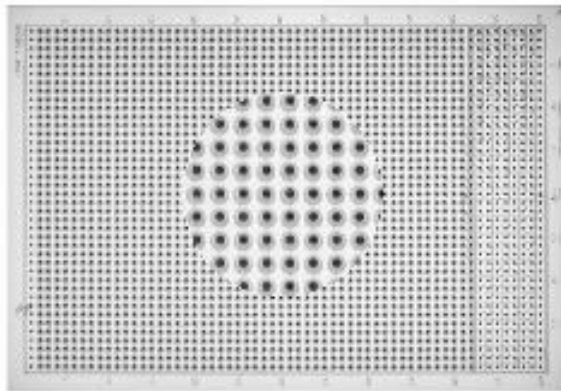
- Square solder pad etched around each hole on wiring side
- Accommodates any type DIP IC device or discrete component




**8004**
**4.5" x 6.5"**

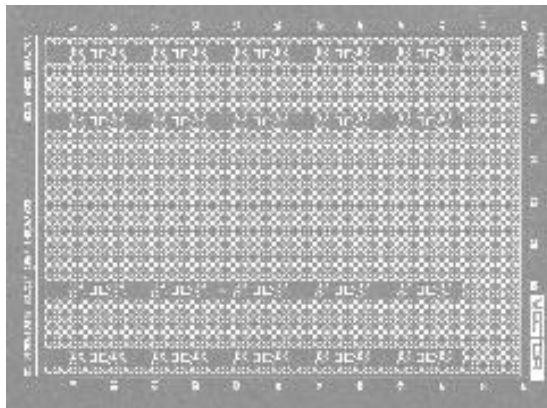
<b>Circuit Pattern:</b>	Ground Plane
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	6.50"/.062"
<b>Height:</b>	4.50"
<b>16-Pin DIP Capacity:</b>	50
<b>Material:</b>	CEM-1
<b>Solder Terminals:</b>	T42-1
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately
- 0.085" diameter clearance around holes
- Etched overall ground plane on wiring side only
- Plane surfaces solder-coated for user convenience
- I/O area with solder pads for mounting connector


**8007**
**4.5" x 6.5"**

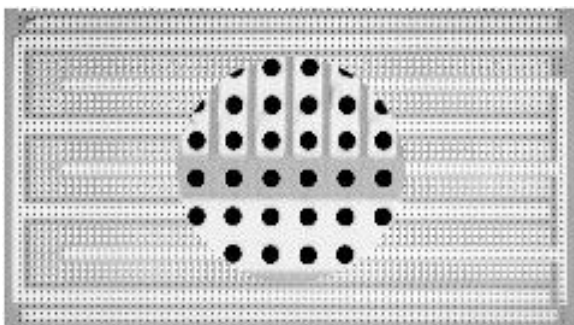
<b>Circuit Pattern:</b>	Pad-Per-Hole/ Ground Plane
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	6.50"/.062"
<b>Height:</b>	4.50"
<b>16-Pin DIP Capacity:</b>	60
<b>Material:</b>	CEM-1
<b>Solder Terminals:</b>	T42-1
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- Pad-Per-Hole pattern on component side - overall Ground Plane pattern on wiring side
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- 0.080" diameter, isolated solder pad around holes, component side
- Accommodates any type DIP IC device or discrete component
- Plane and pad surfaces solder-coated for user convenience


**8008**
**4.5" x 6.5"**

<b>Circuit Pattern:</b>	Pads & Planes
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	6.50"/.062"
<b>Height:</b>	4.50"
<b>16-Pin DIP Capacity:</b>	70
<b>Material:</b>	FR4 Epoxy Glass
<b>Solder Terminals:</b>	T42-1
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- Unique circuit pattern features full voltage and ground planes on opposite sides with isolated, plated-thru holes
- 0.080" diameter, isolated solder pad around holes, component side
- Plane surfaces solder-coated for user convenience
- SMD cap positions for discrete decoupling capacitors

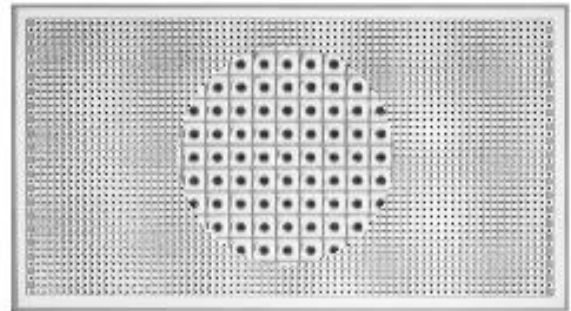

**3677-6**
**4.5" x 8.08"**

<b>Circuit Pattern:</b>	3-Hole Solder Pad
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	8.08"/.062"
<b>Height:</b>	4.50"
<b>16-Pin DIP Capacity:</b>	21
<b>Material:</b>	CEM-1
<b>Solder Terminals:</b>	T42-1
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- Etched circuit pattern on wiring side only
- 0.080" diameter, isolated solder pad around holes, both sides
- 3-hole solder pads (0.028" X 0.080") for interconnecting multiple component leads
- Pad and bus surfaces solder-coated for user convenience

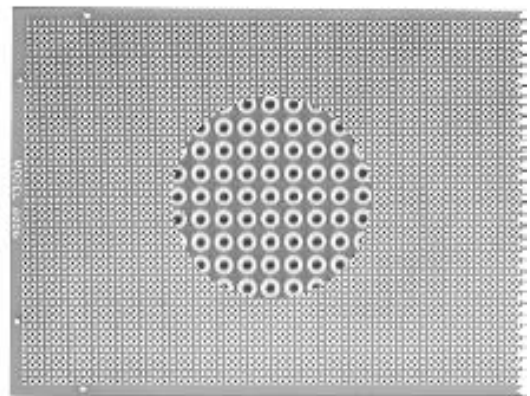
## 45P80-1 4.5" x 8.08"

Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	8.08"/.062"	• Isolated, square pads around each hole
Height:	4.50"	
16-Pin DIP Capacity:	80	
Material:	CEM-1	
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	



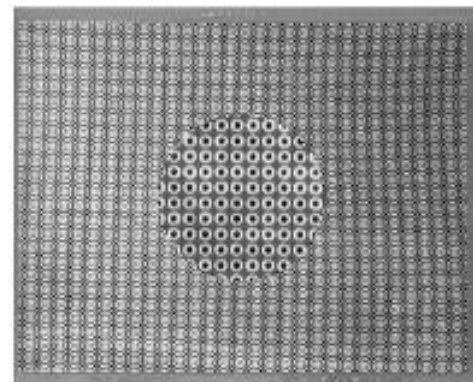
## 8006 5.0" x 13.25"

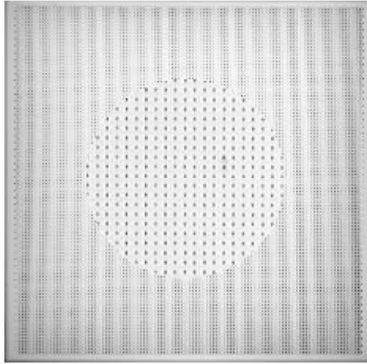
Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	13.25"/.062"	• Copper plated-thru holes
Height:	5.00"	• 0.080" diameter, isolated solder pad around holes, both sides
16-Pin DIP Capacity:	154	• Unrestricted component placement, extended area for high density applications
Material:	FR4 Epoxy Glass	• Board can be cut down into smaller units
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, 49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	



## 8012 9.2" x 11.0"

Circuit Pattern:	Pad-Per-Hole	
Contacts:	N/A	
Width/Thick:	11.00"/.062"	• Plated-thru holes
Height:	9.20"	• Approximates Eurocard (DIN) specifications: 6U x 280MM, can be sheared down to 6U x 220MM, or 160MM
16-Pin DIP Capacity:	283	• 0.080" diameter, isolated solder pad around holes
Material:	FR4 Epoxy Glass	• Unrestricted component placement, extended area for high density applications
Solder Terminals:	T42-1	
Wire-Wrap Terminals:	T44, T46, T49, T68	
Wire-Wrap Socket Pins:	R32	
Hole Diameter:	.042"	

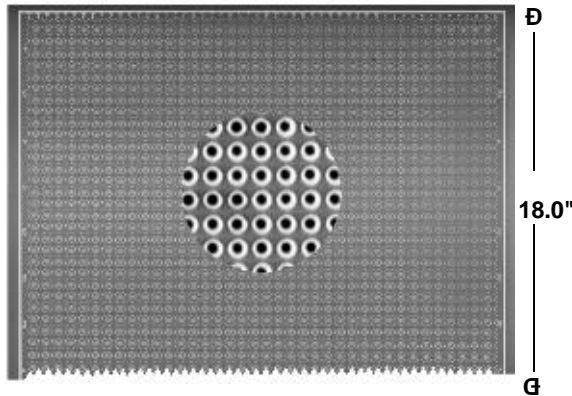




## 106P106-1 10.6" x 10.6"

<b>Circuit Pattern:</b>	Pad-Per-Hole
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	10.60"/.062"
<b>Height:</b>	10.60"
<b>16-Pin DIP Capacity:</b>	275
<b>Material:</b>	FR4 Epoxy Glass
<b>Solder Terminals:</b>	T42-1
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- 0.080" diameter, isolated solder pad around each hole, both sides

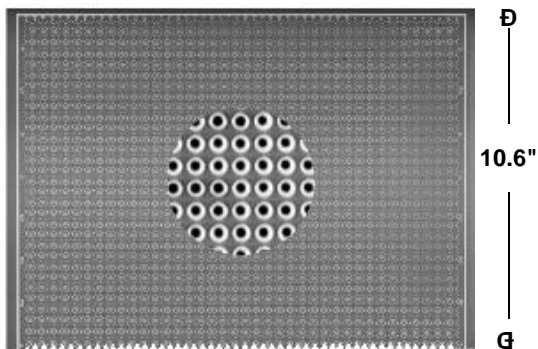


## 106P180-4 10.6" X 18.0"

<b>Circuit Pattern:</b>	Pad-Per-Hole & Ground Plane,
	2 sides
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	10.60"/.062"
<b>Height:</b>	18.00
<b>16-Pin DIP Capacity:</b>	400
<b>Material:</b>	FR4 Epoxy Glass
<b>Solder Terminals:</b>	T42
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- Individual pads with plated-thru holes
- Etched ground plane surrounds pads on both sides
- 0.080" diameter, isolated solder pad around each hole, both sides

## 106P70-4 7.0" x 10.6"



<b>Circuit Pattern:</b>	Pad-Per-Hole & Ground Plane
	N/A
<b>Contacts:</b>	N/A
<b>Width/Thick:</b>	7.0"/.062"
<b>Height:</b>	10.60"
<b>16-Pin DIP Capacity:</b>	175
<b>Material:</b>	FR4 Epoxy Glass
	2 sides
<b>Solder Terminals:</b>	T42-1
<b>Wire-Wrap Terminals:</b>	T44, T46, T49, T68
<b>Wire-Wrap Socket Pins:</b>	R32
<b>Hole Diameter:</b>	.042"

- Individual pads with plated-thru holes
- Etched ground plane surrounds pads on both sides
- 0.080" diameter, isolated solder pad around each hole, both sides

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